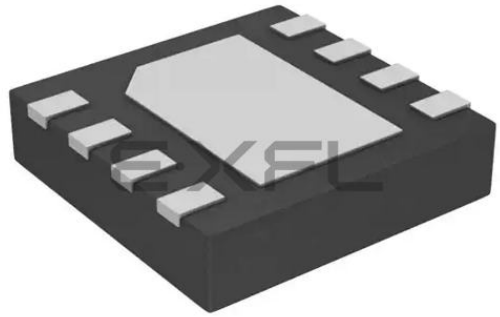

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	LINbus, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	6
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 4x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-UDFN Exposed Pad
Supplier Device Package	8-UDFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12lf1572-e-rf

NOTES:

1.1.2.2 Long Bit Names

Long bit names are constructed by adding a peripheral abbreviation prefix to the short name. The prefix is unique to the peripheral, thereby making every long bit name unique. The long bit name for the COG1 enable bit is the COG1 prefix, G1, appended with the enable bit short name, EN, resulting in the unique bit name G1EN.

Long bit names are useful in both C and assembly programs. For example, in C, the COG1CON0 enable bit can be set with the `G1EN = 1` instruction. In assembly, this bit can be set with the `BSF COG1CON0,G1EN` instruction.

1.1.2.3 Bit Fields

Bit fields are two or more adjacent bits in the same register. Bit fields adhere only to the short bit naming convention. For example, the three Least Significant bits of the COG1CON0 register contain the mode control bits. The short name for this field is MD. There is no long bit name variant. Bit field access is only possible in C programs. The following example demonstrates a C program instruction for setting the COG1 to the Push-Pull mode:

```
COG1CON0bits.MD = 0x5;
```

Individual bits in a bit field can also be accessed with long and short bit names. Each bit is the field name appended with the number of the bit position within the field. For example, the Most Significant mode bit has the short bit name, MD2, and the long bit name is G1MD2. The following two examples demonstrate assembly program sequences for setting the COG1 to Push-Pull mode:

Example 1:

```
MOVLW  ~(1<<G1MD1)
ANDWF  COG1CON0,F
MOVLW  1<<G1MD2 | 1<<G1MD0
IORWF  COG1CON0,F
```

Example 2:

```
BSF    COG1CON0,G1MD2
BCF    COG1CON0,G1MD1
BSF    COG1CON0,G1MD0
```

1.1.3 REGISTER AND BIT NAMING EXCEPTIONS

1.1.3.1 Status, Interrupt and Mirror Bits

Status, interrupt enables, interrupt flags and mirror bits are contained in registers that span more than one peripheral. In these cases, the bit name shown is unique so there is no prefix or short name variant.

1.1.3.2 Legacy Peripherals

There are some peripherals that do not strictly adhere to these naming conventions. Peripherals that have existed for many years and are present in almost every device are the exceptions. These exceptions were necessary to limit the adverse impact of the new conventions on legacy code. Peripherals that do adhere to the new convention will include a table in the registers section indicating the long name prefix for each peripheral instance. Peripherals that fall into the exception category will not have this table. These peripherals include, but are not limited to, the following:

- EUSART
- MSSP

3.3.2 SPECIAL FUNCTION REGISTER

The Special Function Registers are registers used by the application to control the desired operation of peripheral functions in the device. The Special Function Registers occupy the 20 bytes after the core registers of every data memory bank (addresses: x0Ch/x8Ch through x1Fh/x9Fh). The registers associated with the operation of the peripherals are described in the appropriate peripheral chapter of this data sheet.

3.3.3 GENERAL PURPOSE RAM

There are up to 80 bytes of GPR in each data memory bank. The Special Function Registers occupy the 20 bytes after the core registers of every data memory bank (addresses: x0Ch/x8Ch through x1Fh/x9Fh).

3.3.3.1 Linear Access to GPR

The general purpose RAM can be accessed in a non-banked method via the FSRs. This can simplify access to large memory structures. See **Section 3.6.2 "Linear Data Memory"** for more information.

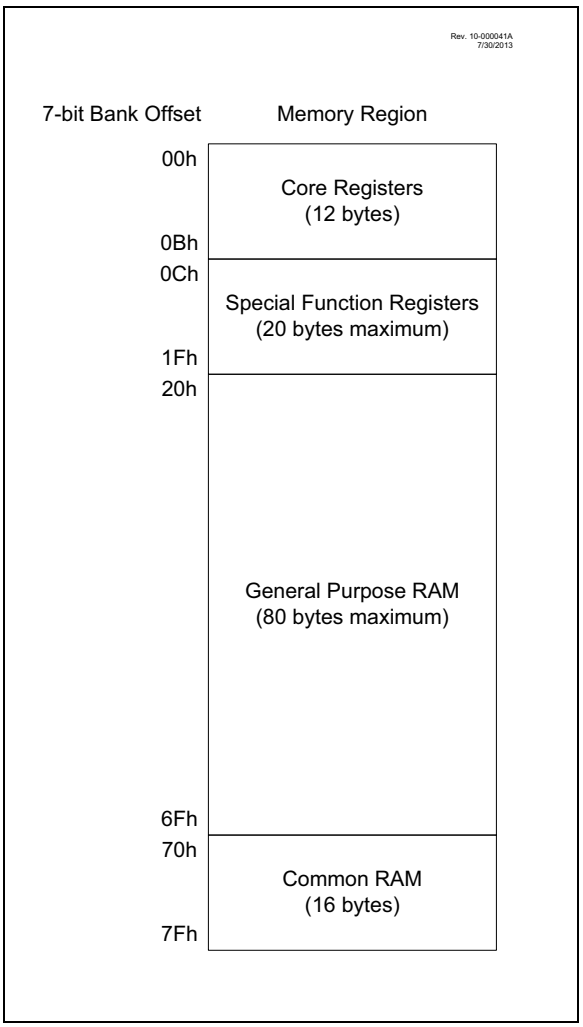
3.3.4 COMMON RAM

There are 16 bytes of common RAM accessible from all banks.

3.3.5 DEVICE MEMORY MAPS

The memory maps for PIC12(L)F1571/2 are as shown in Table 3-3 through Table 3-8.

FIGURE 3-3: BANKED MEMORY PARTITIONING



5.0 OSCILLATOR MODULE

5.1 Overview

The oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications, while maximizing performance and minimizing power consumption. Figure 5-1 illustrates a block diagram of the oscillator module.

Clock sources can be supplied from external oscillators, quartz crystal resonators, ceramic resonators and Resistor-Capacitor (RC) circuits. In addition, the system clock source can be supplied from one of two internal oscillators and PLL circuits, with a choice of speeds selectable via software. Additional clock features include:

- Selectable system clock source between external or internal sources via software
- Oscillator Start-up Timer (OST) ensures stability of crystal oscillator sources

The oscillator module can be configured in one of the following clock modes:

1. ECL – External Clock Low-Power mode (0 MHz to 0.5 MHz)
2. ECM – External Clock Medium Power mode (0.5 MHz to 4 MHz)
3. ECH – External Clock High-Power mode (4 MHz to 32 MHz)
4. INTOSC – Internal Oscillator (31 kHz to 32 MHz)

Clock Source modes are selected by the FOSC<1:0> bits in the Configuration Words. The FOSC bits determine the type of oscillator that will be used when the device is first powered.

The ECH, ECM, and ECL Clock modes rely on an external logic level signal as the device clock source.

The INTOSC internal oscillator block produces low, medium and high-frequency clock sources, designated as LFINTOSC, MFINTOSC and HFINTOSC (see Internal Oscillator Block, Figure 5-1). A wide selection of device clock frequencies may be derived from these three clock sources.

NOTES:

6.4 Low-Power Brown-out Reset (LPBOR)

The Low-Power Brown-out Reset (LPBOR) operates like the BOR to detect low-voltage conditions on the VDD pin. When too low of a voltage is detected, the device is held in Reset. When this occurs, a register bit (BOR) is changed to indicate that a BOR Reset has occurred. The BOR bit in PCON is used for both BOR and the LPBOR. Refer to Register 6-2.

The LPBOR Voltage Threshold (VLPBOR) has a wider tolerance than the BOR (VBOR), but requires much less current (LPBOR current) to operate. The LPBOR is intended for use when the BOR is configured as disabled (BOREN<1:0> = 00) or disabled in Sleep mode (BOREN<1:0> = 10).

Refer to Figure 6-1 to see how the LPBOR interacts with other modules.

6.4.1 ENABLING LPBOR

The LPBOR is controlled by the $\overline{\text{LPBOR}}$ bit of the Configuration Words. When the device is erased, the LPBOR module defaults to disabled.

6.5 $\overline{\text{MCLR}}$

The $\overline{\text{MCLR}}$ is an optional external input that can reset the device. The $\overline{\text{MCLR}}$ function is controlled by the MCLRE and LVP bits of the Configuration Words (Table 6-2).

TABLE 6-2: $\overline{\text{MCLR}}$ CONFIGURATION

MCLRE	LVP	$\overline{\text{MCLR}}$
0	0	Disabled
1	0	Enabled
x	1	Enabled

6.5.1 $\overline{\text{MCLR}}$ ENABLED

When $\overline{\text{MCLR}}$ is enabled and the pin is held low, the device is held in Reset. The $\overline{\text{MCLR}}$ pin is connected to VDD through an internal weak pull-up.

The device has a noise filter in the $\overline{\text{MCLR}}$ Reset path. The filter will detect and ignore small pulses.

Note:	A Reset does not drive the $\overline{\text{MCLR}}$ pin low.

6.5.2 $\overline{\text{MCLR}}$ DISABLED

When $\overline{\text{MCLR}}$ is disabled, the pin functions as a general purpose input and the internal weak pull-up is under software control. See **Section 11.3 "PORTA Registers"** for more information.

6.6 Watchdog Timer (WDT) Reset

The Watchdog Timer generates a Reset if the firmware does not issue a CLRWDT instruction within the time-out period. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits in the STATUS register are changed to indicate the WDT Reset. See **Section 9.0 "Watchdog Timer (WDT)"** for more information.

6.7 RESET Instruction

A RESET instruction will cause a device Reset. The $\overline{\text{RI}}$ bit in the PCON register will be set to '0'. See Table 6-4 for default conditions after a RESET instruction has occurred.

6.8 Stack Overflow/Underflow Reset

The device can reset when the Stack overflows or underflows. The STKOVF or STKUNF bits of the PCON register indicate the Reset condition. These Resets are enabled by setting the STVREN bit in the Configuration Words. See **Section 3.5.2 "Overflow/Underflow Reset"** for more information.

6.9 Programming Mode Exit

Upon exit of Programming mode, the device will behave as if a POR had just occurred.

6.10 Power-up Timer

The Power-up Timer optionally delays device execution after a BOR or POR event. This timer is typically used to allow VDD to stabilize before allowing the device to start running.

The Power-up Timer is controlled by the $\overline{\text{PWRTE}}$ bit of the Configuration Words.

6.11 Start-up Sequence

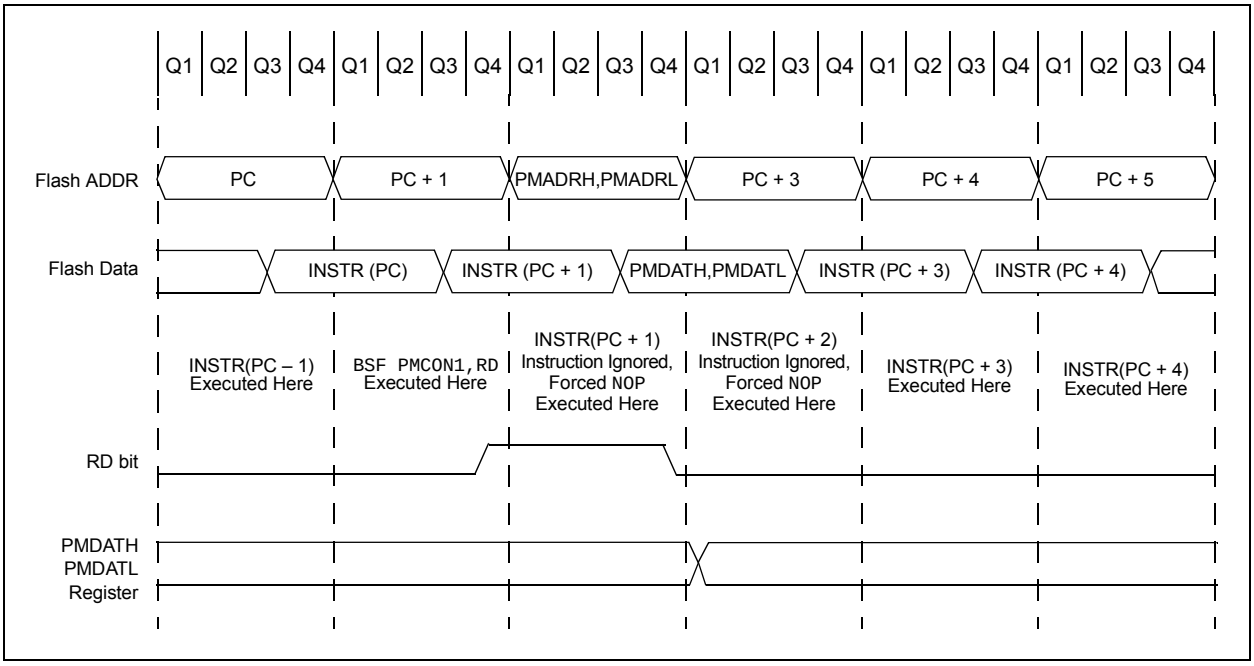
Upon the release of a POR or BOR, the following must occur before the device will begin executing:

1. Power-up Timer runs to completion (if enabled).
2. $\overline{\text{MCLR}}$ must be released (if enabled).

The total time-out will vary based on oscillator configuration and Power-up Timer configuration. See **Section 5.0 "Oscillator Module"** for more information.

The Power-up Timer runs independently of a $\overline{\text{MCLR}}$ Reset. If $\overline{\text{MCLR}}$ is kept low long enough, the Power-up Timer will expire. Upon bringing $\overline{\text{MCLR}}$ high, the device will begin execution after 10 FOSC cycles (see Figure 6-3). This is useful for testing purposes or to synchronize more than one device operating in parallel.

FIGURE 10-2: FLASH PROGRAM MEMORY READ CYCLE EXECUTION



EXAMPLE 10-1: FLASH PROGRAM MEMORY READ

```
* This code block will read 1 word of program
* memory at the memory address:
    PROG_ADDR_HI : PROG_ADDR_LO
*   data will be returned in the variables;
*   PROG_DATA_HI, PROG_DATA_LO

    BANKSEL  PMADRL           ; Select Bank for PMCON registers
    MOVLW    PROG_ADDR_LO     ;
    MOVWF    PMADRL           ; Store LSB of address
    MOVLW    PROG_ADDR_HI     ;
    MOVWF    PMADRH           ; Store MSB of address

    BCF      PMCON1,CFGS      ; Do not select Configuration Space
    BSF      PMCON1,RD        ; Initiate read
    NOP                       ; Ignored (Figure 10-2)
    NOP                       ; Ignored (Figure 10-2)

    MOVF     PMDATL,W         ; Get LSB of word
    MOVWF    PROG_DATA_LO     ; Store in user location
    MOVF     PMDATH,W         ; Get MSB of word
    MOVWF    PROG_DATA_HI     ; Store in user location
```

10.6 Register Definitions: Flash Program Memory Control

REGISTER 10-1: PMDATL: PROGRAM MEMORY DATA LOW BYTE REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
PMDAT<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	
u = Bit is unchanged	x = Bit is unknown	U = Unimplemented bit, read as ‘0’
‘1’ = Bit is set	‘0’ = Bit is cleared	-n/n = Value at POR and BOR/Value at all other Resets

bit 7-0 **PMDAT<7:0>**: Read/Write Value for Least Significant bits of Program Memory bits

REGISTER 10-2: PMDATH: PROGRAM MEMORY DATA HIGH BYTE REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	PMDAT<13:8>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	
u = Bit is unchanged	x = Bit is unknown	U = Unimplemented bit, read as ‘0’
‘1’ = Bit is set	‘0’ = Bit is cleared	-n/n = Value at POR and BOR/Value at all other Resets

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **PMDAT<13:8>**: Read/Write Value for Most Significant bits of Program Memory bits

NOTES:

NOTES:

14.0 TEMPERATURE INDICATOR MODULE

This family of devices is equipped with a temperature circuit designed to measure the operating temperature of the silicon die. The circuit's range of operating temperature falls between -40°C and +85°C. The output is a voltage that is proportional to the device temperature. The output of the temperature indicator is internally connected to the device ADC.

The circuit may be used as a temperature threshold detector or a more accurate temperature indicator, depending on the level of calibration performed. A one-point calibration allows the circuit to indicate a temperature closely surrounding that point. A two-point calibration allows the circuit to sense the entire range of temperature more accurately. Reference Application Note AN1333, "*Use and Calibration of the Internal Temperature Indicator*" (DS00001333) for more details regarding the calibration process.

14.1 Circuit Operation

Figure 14-1 shows a simplified block diagram of the temperature circuit. The proportional voltage output is achieved by measuring the forward voltage drop across multiple silicon junctions.

Equation 14-1 describes the output characteristics of the temperature indicator.

EQUATION 14-1: VOUT RANGES

$$\text{High Range: } V_{OUT} = V_{DD} - 4V_T$$

$$\text{Low Range: } V_{OUT} = V_{DD} - 2V_T$$

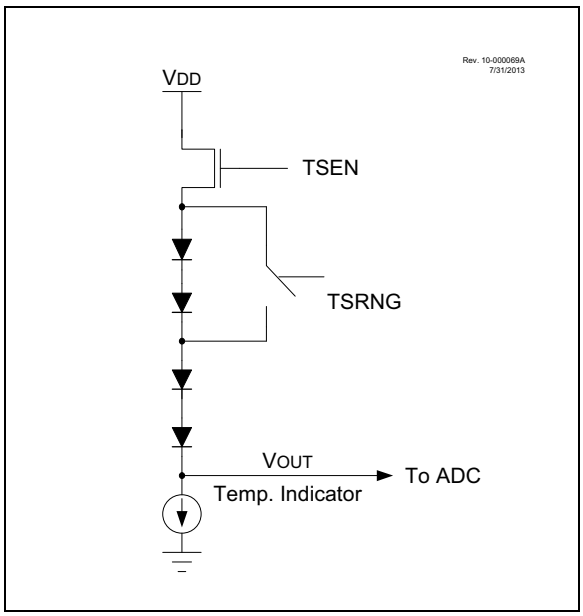
The temperature sense circuit is integrated with the Fixed Voltage Reference (FVR) module. See **Section 13.0 "Fixed Voltage Reference (FVR)"** for more information.

The circuit is enabled by setting the TSEN bit of the FVRCON register. When disabled, the circuit draws no current.

The circuit operates in either high or low range. The high range, selected by setting the TSRNG bit of the FVRCON register, provides a wider output voltage. This provides more resolution over the temperature range, but may be less consistent from part to part. This range requires a higher bias voltage to operate and thus, a higher VDD is needed.

The low range is selected by clearing the TSRNG bit of the FVRCON register. The low range generates a lower voltage drop and thus, a lower bias voltage is needed to operate the circuit. The low range is provided for low-voltage operation.

FIGURE 14-1: TEMPERATURE CIRCUIT DIAGRAM



14.2 Minimum Operating VDD

When the temperature circuit is operated in low range, the device may be operated at any operating voltage that is within specifications.

When the temperature circuit is operated in high range, the device operating voltage, VDD, must be high enough to ensure that the temperature circuit is correctly biased.

Table 14-1 shows the recommended minimum VDD vs. range setting.

TABLE 14-1: RECOMMENDED VDD VS. RANGE

Min. VDD, TSRNG = 1	Min. VDD, TSRNG = 0
3.6V	1.8V

14.3 Temperature Output

The output of the circuit is measured using the internal Analog-to-Digital Converter. A channel is reserved for the temperature circuit output. Refer to **Section 15.0 "Analog-to-Digital Converter (ADC) Module"** for detailed information.

14.4 ADC Acquisition Time

To ensure accurate temperature measurements, the user must wait at least 200 μs after the ADC input multiplexer is connected to the temperature indicator output before the conversion is performed. In addition, the user must wait 200 μs between sequential conversions of the temperature indicator output.

REGISTER 21-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R-0/0	R-0/0	R-0/0
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	
u = Bit is unchanged	x = Bit is unknown	U = Unimplemented bit, read as ‘0’
‘1’ = Bit is set	‘0’ = Bit is cleared	-n/n = Value at POR and BOR/Value at all other Resets

bit 7 **SPEN:** Serial Port Enable bit

1 = Serial port is enabled (configures RX/DT and TX/CK pins as serial port pins)
0 = Serial port is disabled (held in Reset)

bit 6 **RX9:** 9-Bit Receive Enable bit

1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5 **SREN:** Single Receive Enable bit

Asynchronous mode:
Don’t care.

Synchronous mode – Master:
1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.

Synchronous mode – Slave:
Don’t care.

bit 4 **CREN:** Continuous Receive Enable bit

Asynchronous mode:
1 = Enables receiver
0 = Disables receiver

Synchronous mode:
1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
0 = Disables continuous receive

bit 3 **ADDEN:** Address Detect Enable bit

Asynchronous mode 9-bit (RX9 = 1):
1 = Enables address detection, enables interrupt and loads the receive buffer when RSR<8> is set
0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit

Asynchronous mode 8-bit (RX9 = 0):
Don’t care.

bit 2 **FERR:** Framing Error bit

1 = Framing error (can be updated by reading RCREG register and receiving next valid byte)
0 = No framing error

bit 1 **OERR:** Overrun Error bit

1 = Overrun error (can be cleared by clearing bit, CREN)
0 = No overrun error

bit 0 **RX9D:** Ninth Bit of Received Data bit

This can be address/data bit or a parity bit and must be calculated by user firmware.

21.5.2 SYNCHRONOUS SLAVE MODE

The following bits are used to configure the EUSART for synchronous slave operation:

- SYNC = 1
- CSRC = 0
- SREN = 0 (for transmit); SREN = 1 (for receive)
- CREN = 0 (for transmit); CREN = 1 (for receive)
- SPEN = 1

Setting the SYNC bit of the TXSTA register configures the device for synchronous operation. Clearing the CSRC bit of the TXSTA register configures the device as a slave. Clearing the SREN and CREN bits of the RCSTA register ensures that the device is in Transmit mode; otherwise, the device will be configured to receive. Setting the SPEN bit of the RCSTA register enables the EUSART.

21.5.2.1 EUSART Synchronous Slave Transmit

The operation of the Synchronous Master and Slave modes is identical (see **Section 21.5.1.3 "Synchronous Master Transmission")**, except in the case of Sleep mode.

If two words are written to the TXREG and then the SLEEP instruction is executed, the following will occur:

1. The first character will immediately transfer to the TSR register and transmit.
2. The second word will remain in the TXREG register.
3. The TXIF bit will not be set.
4. After the first character has been shifted out of TSR, the TXREG register will transfer the second character to the TSR and the TXIF bit will now be set.
5. If the PEIE and TXIE bits are set, the interrupt will wake the device from Sleep and execute the next instruction. If the GIE bit is also set, the program will call the Interrupt Service Routine.

21.5.2.2 Synchronous Slave Transmission Setup

1. Set the SYNC and SPEN bits, and clear the CSRC bit.
2. Clear the ANSELx bit for the CK pin (if applicable).
3. Clear the CREN and SREN bits.
4. If interrupts are desired, set the TXIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. If 9-bit transmission is desired, set the TX9 bit.
6. Enable transmission by setting the TXEN bit.
7. If 9-bit transmission is selected, insert the Most Significant bit into the TX9D bit.
8. Start transmission by writing the Least Significant eight bits to the TXREG register.

TABLE 21-9: SUMMARY OF REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	186
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	74
PIE1	TMR1GIE	ADIE	RCIE(1)	TXIE(1)	—	—	TMR2IE	TMR1IE	75
PIR1	TMR1GIF	ADIF	RCIF(1)	TXIF(1)	—	—	TMR2IF	TMR1IF	78
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	185
TXREG	EUSART Transmit Data Register								177*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	184

Legend: — = unimplemented location, read as '0'. Shaded cells are not used for synchronous slave transmission.

* Page provides register information.

Note 1: PIC12(L)F1572 only.

FIGURE 22-12: OFFSET MATCH ON INCREMENTING TIMER TIMING DIAGRAM

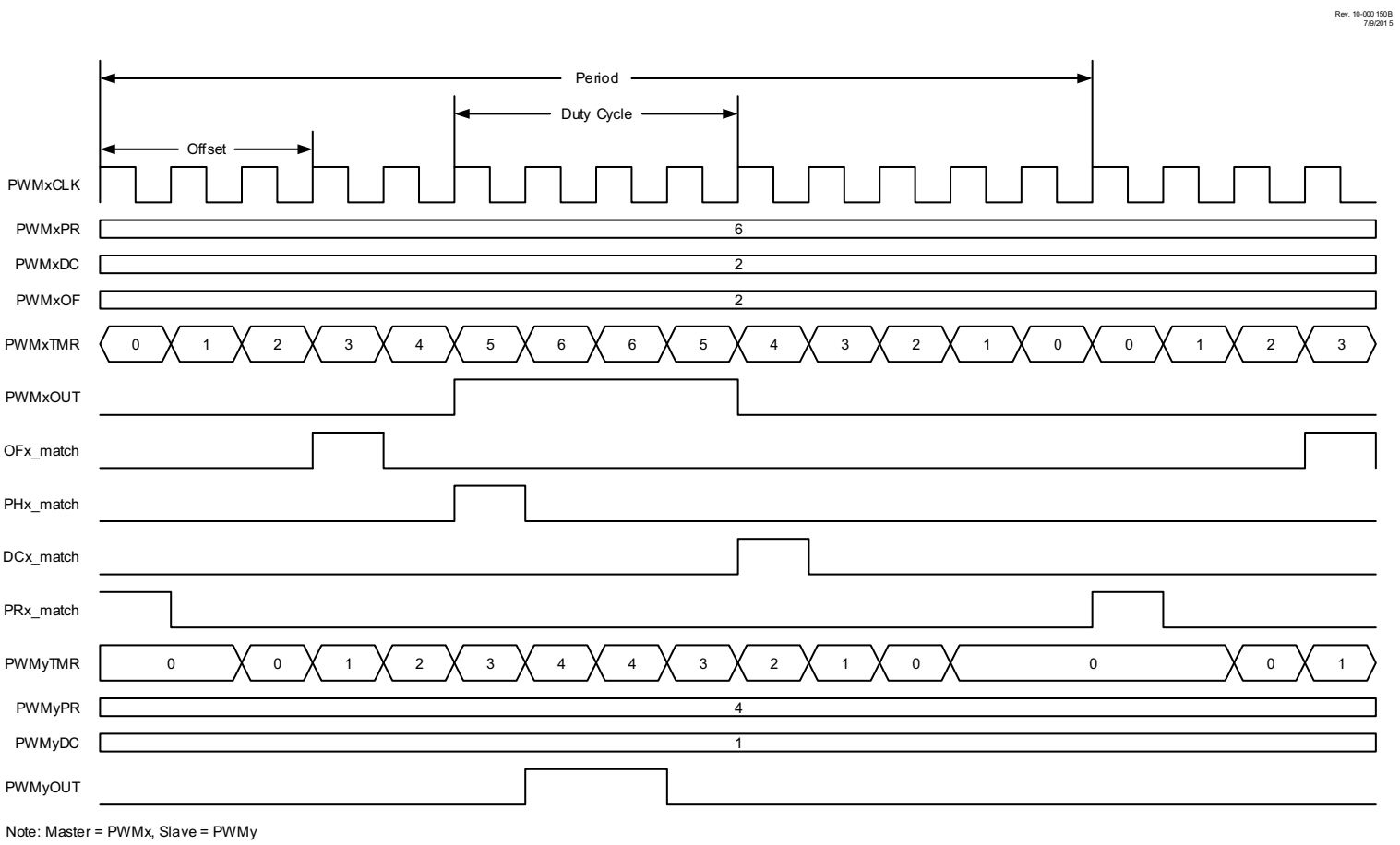


TABLE 26-3: POWER-DOWN CURRENTS (I_{PD})(1,2) (CONTINUED)

PIC12LF1571/2		Operating Conditions (unless otherwise stated) Low-Power Sleep Mode						
PIC12F1571/2		Low-Power Sleep Mode, VREGPM = 1						
Param. No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							V_{DD}	Note
D027		—	4	7	9	µA	1.8	Comparator, CxSP = 0
		—	4.2	8	10	µA	3.0	
D027		—	13	20	21	µA	2.3	Comparator, CxSP = 0
		—	14	23	25	µA	3.0	
		—	16	24	26	µA	5.0	
D028A		—	20	35	36	µA	1.8	Comparator, Normal Power, CxSP = 1 **(Note 1)**
		—	21	36	38	µA	3.0	
D028A		—	28	47	48	µA	2.3	Comparator, Normal Power, CxSP = 1, VREGPM = 1 **(Note 1)**
		—	29	51	52	µA	3.0	
		—	31	52	53	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, +25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral Δ current can be determined by subtracting the base I_{PD} current from this limit. Max. values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{SS}.

3: ADC clock source is FRC.

TABLE 26-4: I/O PORTS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O Ports:					
D030		with TTL Buffer	—	—	0.8	V	4.5V ≤ VDD ≤ 5.5V
D030A			—	—	0.15 VDD	V	1.8V ≤ VDD ≤ 4.5V
D031		with Schmitt Trigger Buffer	—	—	0.2 VDD	V	2.0V ≤ VDD ≤ 5.5V
		with I^2C Levels	—	—	0.3 VDD	V	
		with SMbus Levels	—	—	0.8	V	2.7V ≤ VDD ≤ 5.5V
D032		$\overline{MCLR}$	—	—	0.2 VDD	V	
	VIH	**Input High Voltage**					
		I/O Ports:					
D040		with TTL Buffer	2.0	—	—	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25 VDD + 0.8	—	—	V	1.8V ≤ VDD ≤ 4.5V
D041		with Schmitt Trigger Buffer	0.8 VDD	—	—	V	2.0V ≤ VDD ≤ 5.5V
		with I^2C Levels	0.7 VDD	—	—	V	
		with SMbus Levels	2.1	—	—	V	2.7V ≤ VDD ≤ 5.5V
D042		$\overline{MCLR}$	0.8 VDD	—	—	V	
	IIL	**Input Leakage Current(1)**					
D060		I/O Ports	—	± 5	± 125	nA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, +85°C
			—	± 5	± 1000	nA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, +125°C
D061		$\overline{MCLR}$(2)	—	± 50	± 200	nA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, +85°C
	IPUR	**Weak Pull-up Current**					
D070*			25	100	200	µA	VDD = 3.3V, VPIN = VSS
			25	140	300	µA	VDD = 5.0V, VPIN = VSS
	VOL	**Output Low Voltage**					
D080		I/O Ports	—	—	0.6	V	IOL = 8 mA, VDD = 5V IOL = 6 mA, VDD = 3.3V IOL = 1.8 mA, VDD = 1.8V
	VOH	**Output High Voltage**					
D090		I/O Ports	VDD – 0.7	—	—	V	IOH = 3.5 mA, VDD = 5V IOH = 3 mA, VDD = 3.3V IOH = 1 mA, VDD = 1.8V
		Capacitive Loading Specifications on Output Pins					
D101A*	CIO	All I/O Pins	—	—	50	pF	

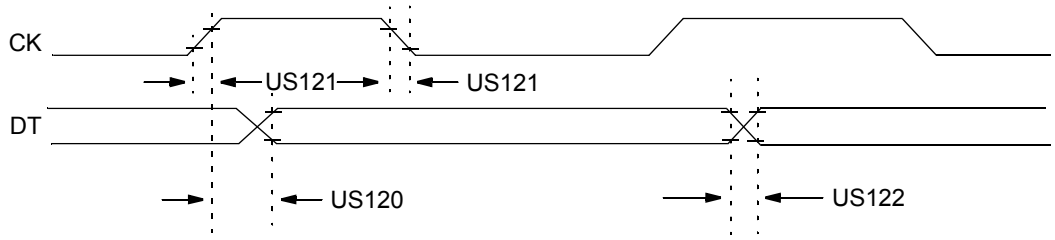
* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, +25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Negative current is defined as current sourced by the pin.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

FIGURE 26-13: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

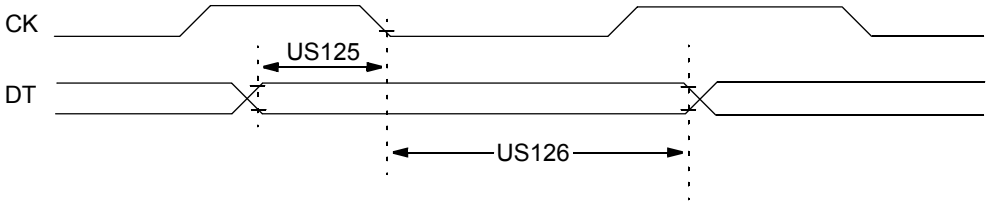


Note: Refer to Figure 26-4 for load conditions.

TABLE 26-17: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)						
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Max.**	**Units**	**Conditions**
US120	TCKH2DTV	SYNC XMIT (Master and Slave) Clock High to Data-Out Valid	—	80	ns	3.0V ≤ VDD ≤ 5.5V
			—	100	ns	1.8V ≤ VDD ≤ 5.5V
US121	TCKRF	Clock Out Rise Time and Fall Time (Master mode)	—	45	ns	3.0V ≤ VDD ≤ 5.5V
			—	50	ns	1.8V ≤ VDD ≤ 5.5V
US122	TDTRF	Data-Out Rise Time and Fall Time	—	45	ns	3.0V ≤ VDD ≤ 5.5V
			—	50	ns	1.8V ≤ VDD ≤ 5.5V

FIGURE 26-14: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 26-4 for load conditions.

TABLE 26-18: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)						
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Max.**	**Units**	**Conditions**
US125	TDTV2CKL	SYNC RCV (Master and Slave) Data-Hold before CK ↓ (DT hold time)	10	—	ns	
US126	TCKL2DTL	Data-Hold after CK ↓ (DT hold time)	15	—	ns	

FIGURE 27-23: IPD, WATCHDOG TIMER (WDT), PIC12LF1571/2 ONLY

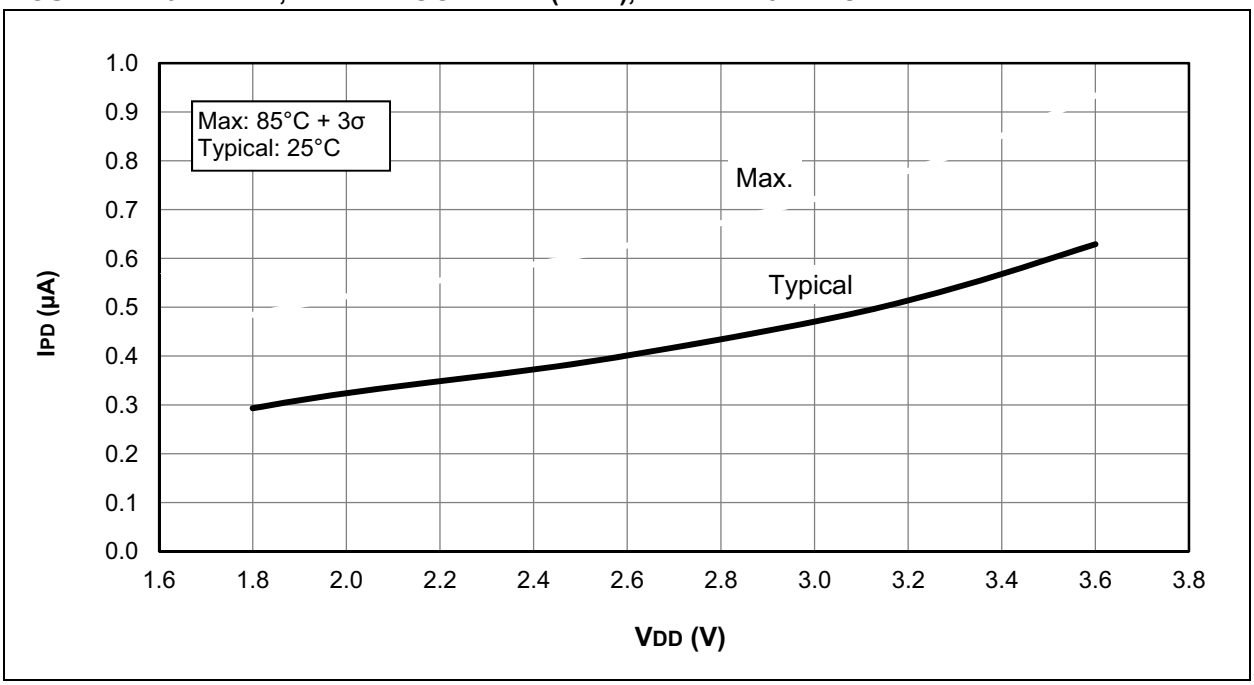
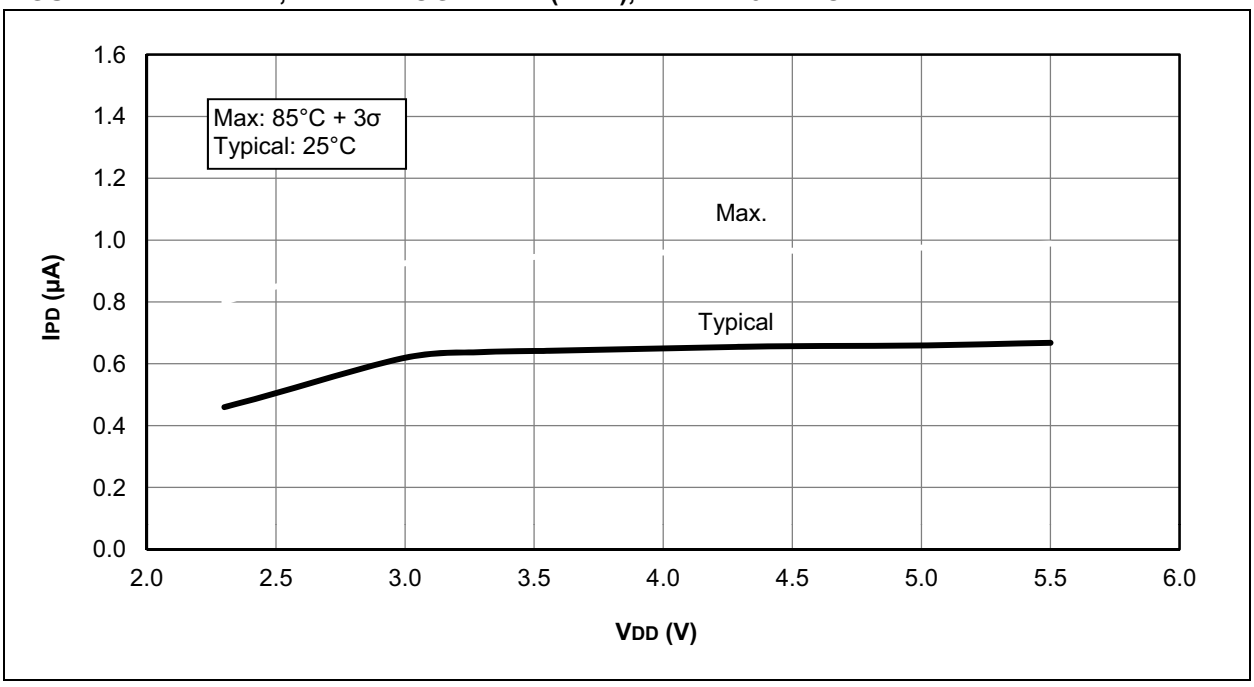


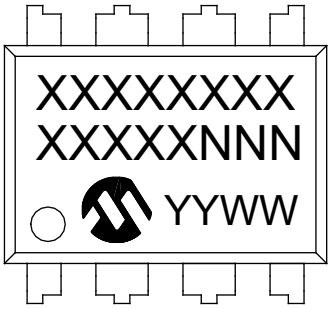
FIGURE 27-24: IPD, WATCHDOG TIMER (WDT), PIC12F1571/2 ONLY



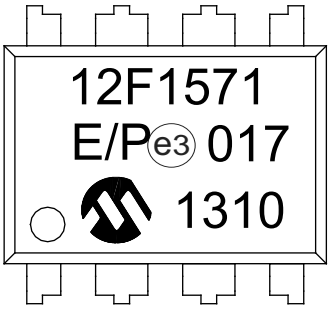
29.0 PACKAGING INFORMATION

29.1 Package Marking Information

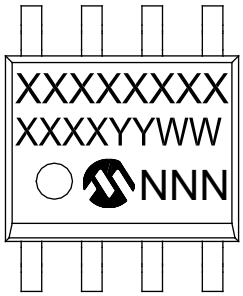
8-Lead PDIP (300 mil)



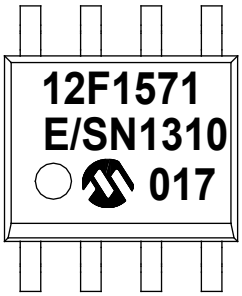
Example



8-Lead SOIC (3.90 mm)



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

NOTES: